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(54) **DISPLAY DEVICE**

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(57) **ABSTRACT**

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(63) Continuation of application No. 18/138,530, filed on Apr. 24, 2023, now Pat. No. 11,980,051, which is a continuation of application No. 17/710,426, filed on Mar. 31, 2022, now Pat. No. 11,672,142, which is a continuation of application No. 16/716,817, filed on Dec. 17, 2019, now Pat. No. 11,329,255.

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Discussed is a display device including an organic light emitting device in a display area on a substrate, a thin film transistor connected with the organic light emitting device, a planarization layer on the thin film transistor, a protecting portion on a buffer area on the substrate, the protecting portion surrounding at least a portion of a camera area on the substrate, the buffer area disposed between the display area and the camera area, a dam structure on the buffer area, the dam structure apart from the protecting portion, an encapsulation layer including a first encapsulation layer, a second encapsulation layer on the first encapsulation layer, and a third encapsulation layer on the second encapsulation layer, and a hole in the camera area, the hole provided inside the display area. The first encapsulation layer and the third encapsulation layer are disposed on a side surface of the planarization layer.

